



Smart TSV Repair Automation in 3DIC Designs

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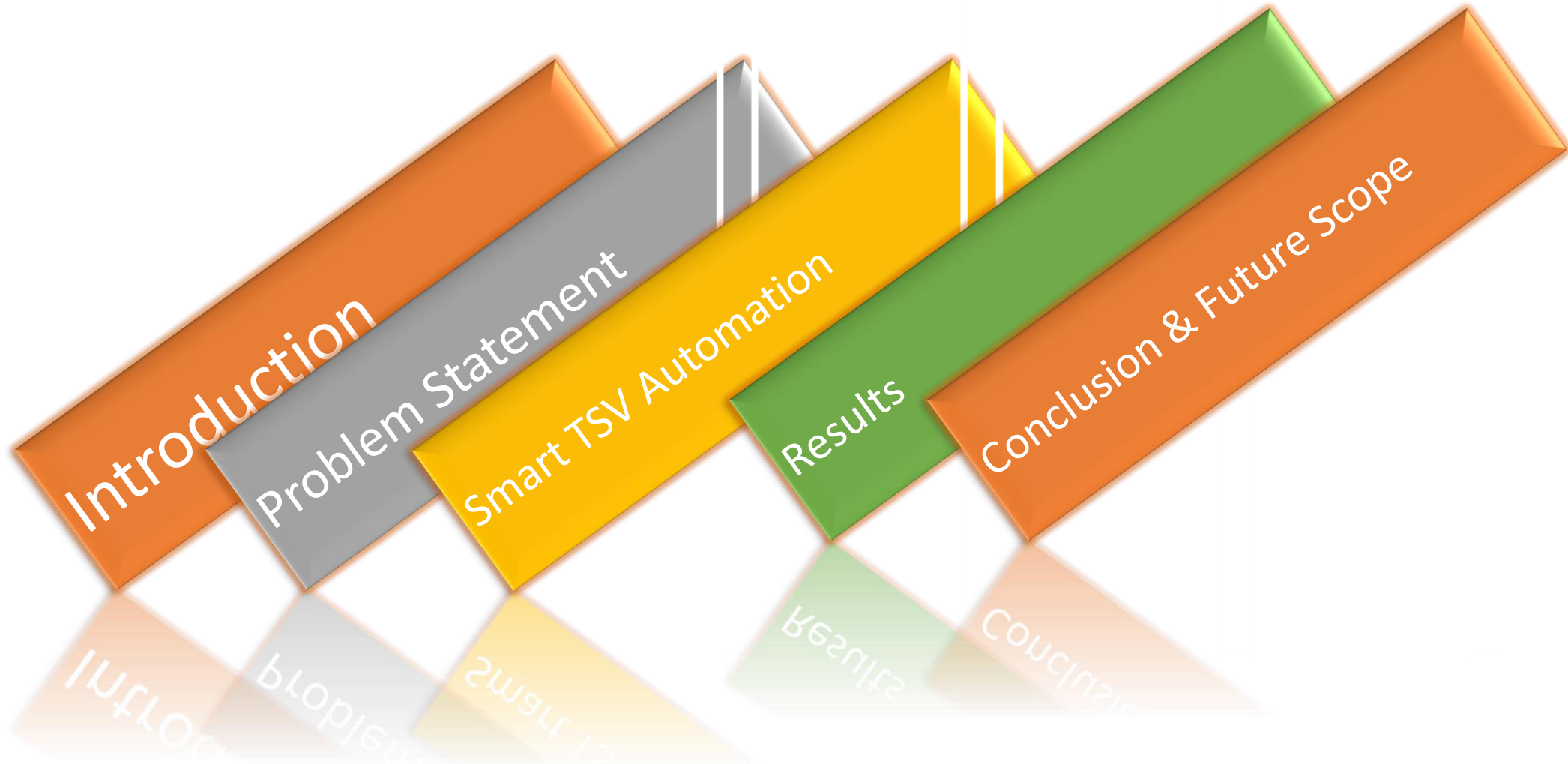
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SAMSUNG



Agenda

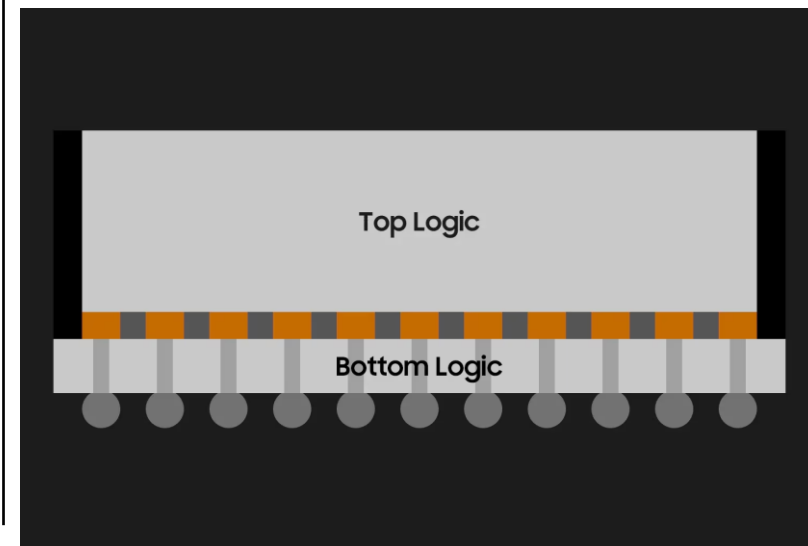
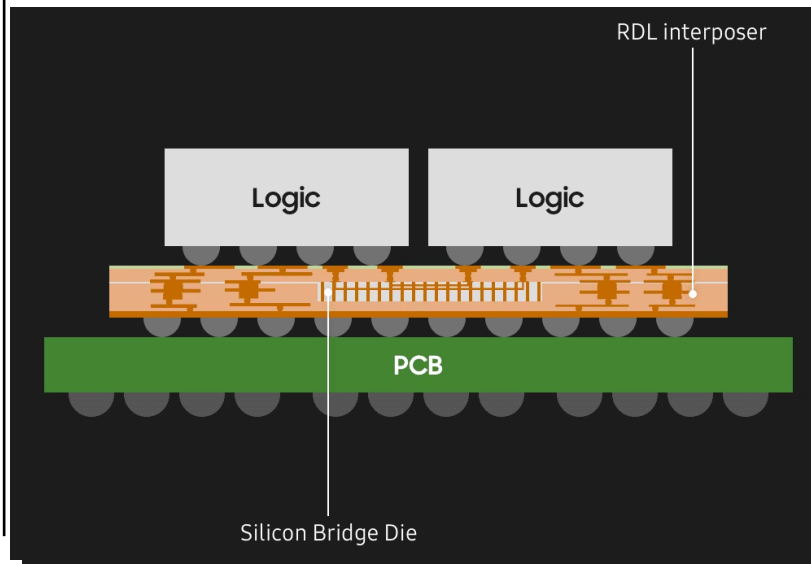
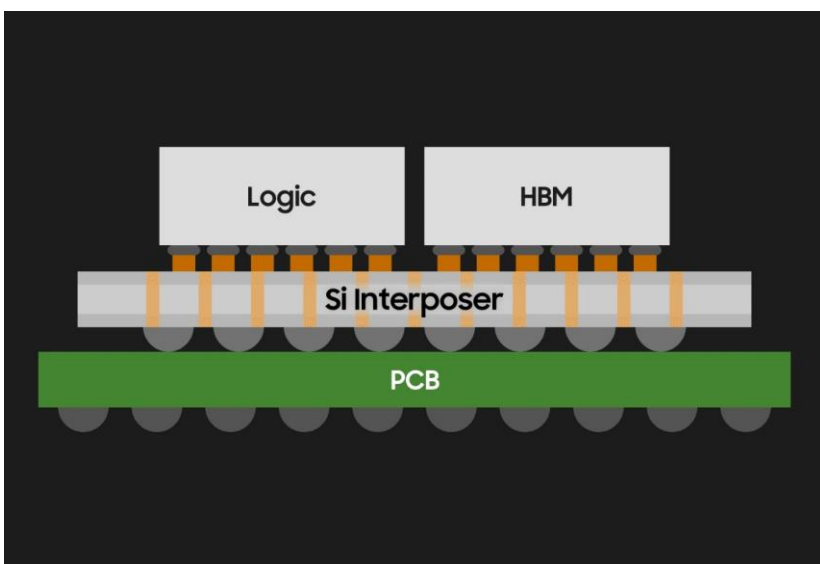


Introduction

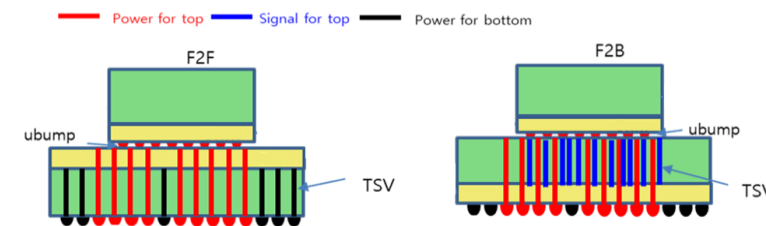
Introduction

HORIZONTAL INTEGRATION (2.5D)

X-CUBE (3DIC) (VERTICAL INTEGRATION)



- 3DIC is most prominent technology advancement in Semiconductor Industry
- Offers Low latency, Higher bandwidth and package density
 - Shorter inter-connect lengths
- Heterogeneous Die Integration

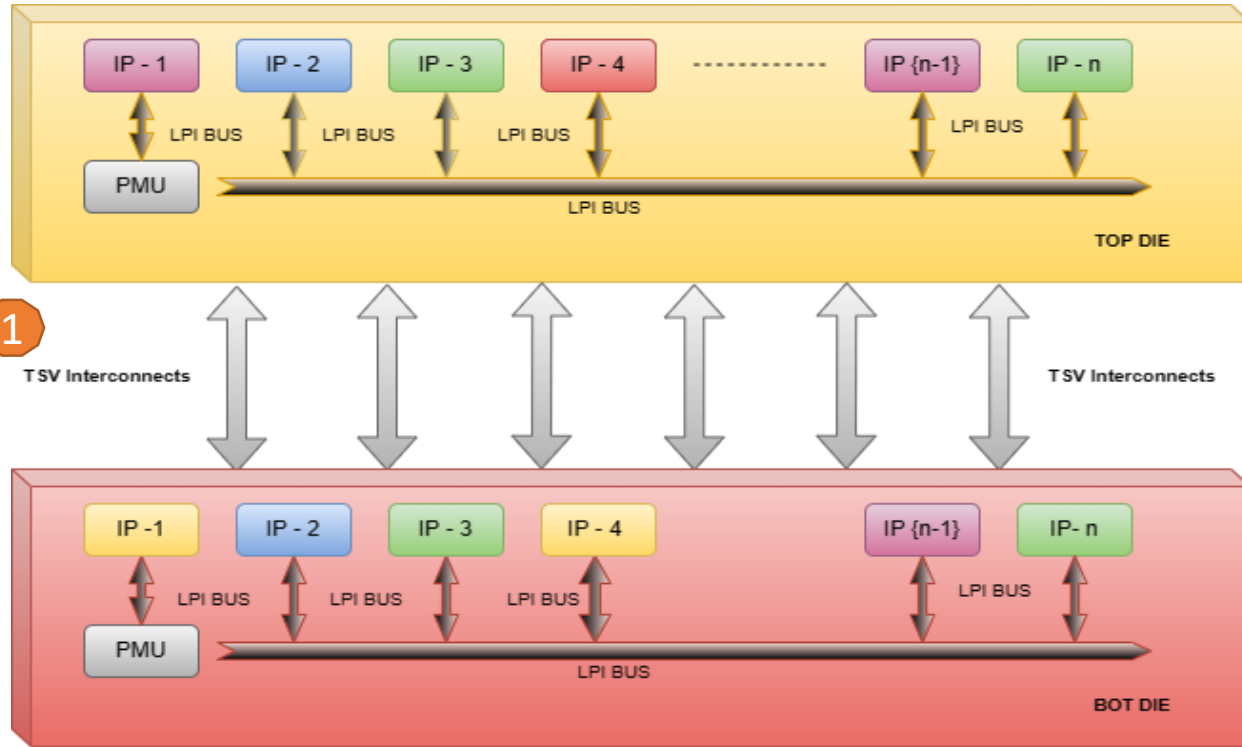




Problem Statement

3DIC LOGIC DIEs

Faulty TSVs & Impact



2 Power TSV

Carries power from bottom die to upper dies

- Catastrophic
- Impacts the yield directly

Signal TSV

Control and Data Signal TSVs between Dies

- Limits the design functionality (Hang situation, Integrity failures)
- Control Signal TSV → Hang situation – Timeout
- Data Signal TSV → Integrity failures – CRC, ECC, Parity issues

Pad TSV

Input/Output/In-Out pads from Bottom ↔ Top

- Impacts functionality stacked dies in certain ways
- Interrupt propagation
- External Ref clock stuck

3	BLK	Fault Metrics			Fault Classification			
		Groups	No. of TSVs per group	No. of Faults	Fault Spectrum	Ctrl Path	Data Path	LPI
	BLK A (Die to Die)	965	18	34740	5.56%	10422	5211	1737
	BLK B (Memory Access)	554	32	35456	3.13%	5318	10637	1773
	BLK C (Other IPs)	298	36	21456	2.78%	2146	7510	1073



Smart TSV Automation

Verification Challenges



Multitude number of tests to cover all TSVs (Functional & Gate Sims)



Repair Signature generation



Connectivity of TSVs across logical dies

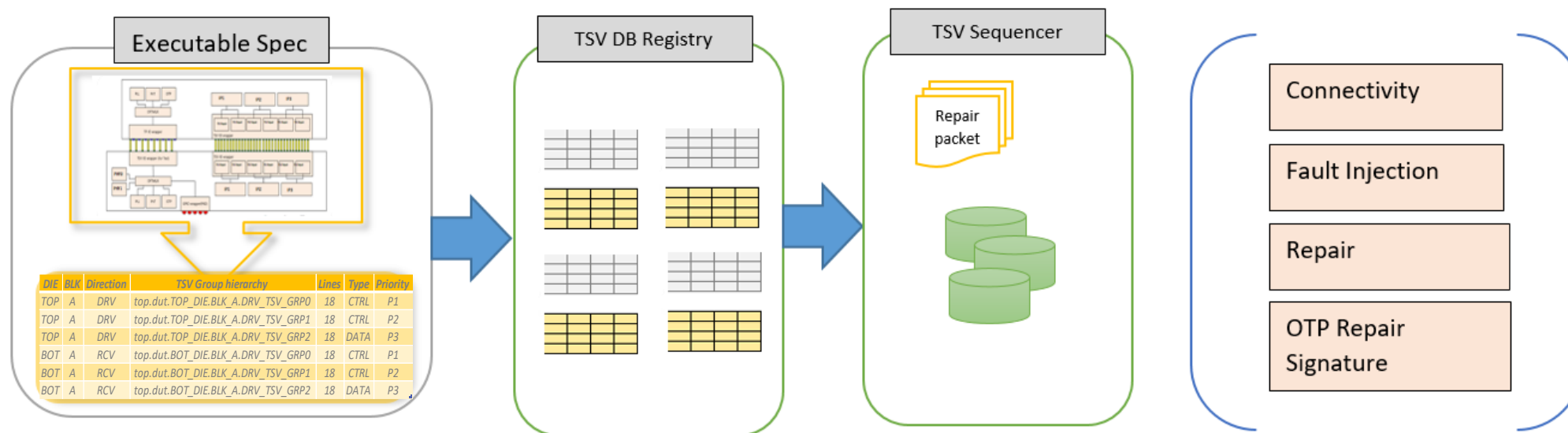


A Bug escape can lead to potential issues



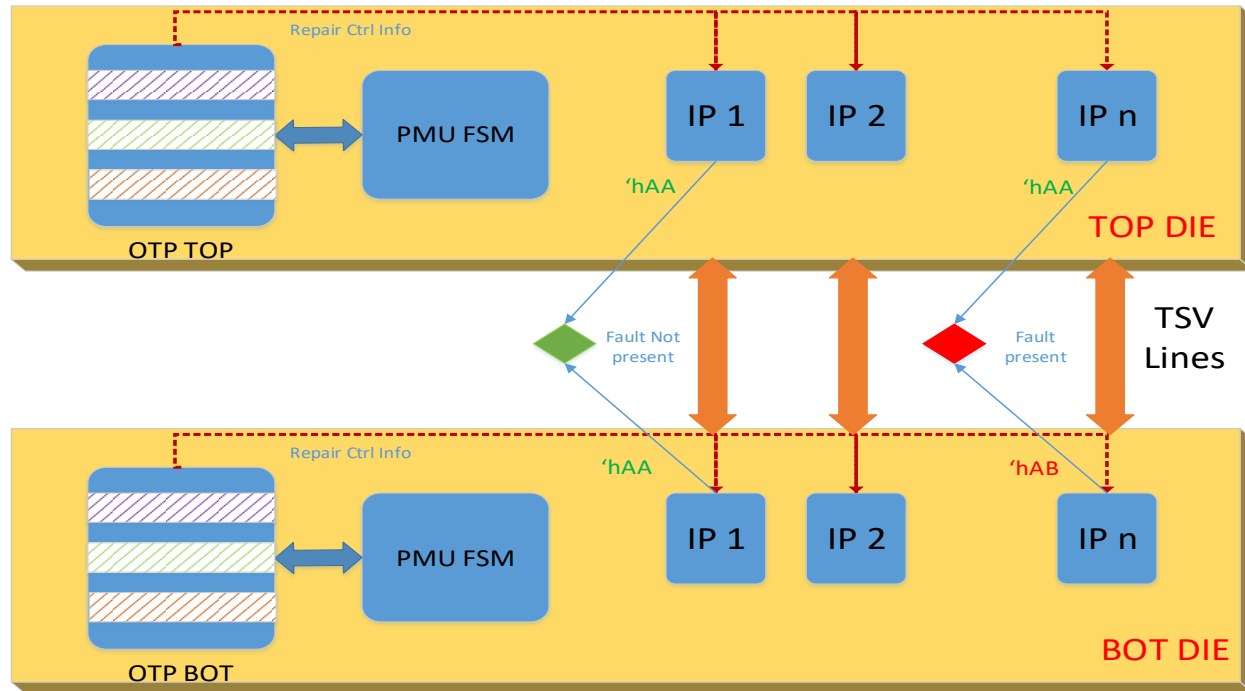
Coverage closure

Automation - Concept



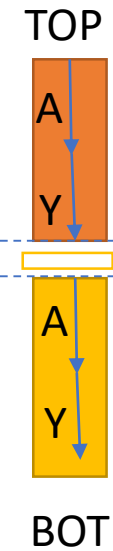
- Fully automated Sequences/APIs
- Embedded functional coverage instrumentation
- Random/Directed-random faults selection and OTP repair packets selection
- APIs for further writing custom test scenarios
- Test case Pruning with coverage-aware stimuli generator

TSV Connectivity



- OTP Repair signature connectivity
- TSV connectivity between dies

TSV Connectivity



TOP Die DRV
Signals

```
* Driver Side
Ver /top/dut/ _TOP/BLK_ /TSV_REPAIR_PD_CORE/DK_DRV_grp1/A[31:0]
Ver /top/dut/ _TOP/BLK_ /TSV_REPAIR_PD_CORE/DK_DRV_grp1/Y[31:0]
* Receiver Side
Ver /top/dut/ _BOT/BLK_ BOT/TSV_REPAIR_PD_CORE/DK_RCV_grp1/A[31:0]
Ver /top/dut/ _BOT/BLK_ BOT/TSV_REPAIR_PD_CORE/DK_RCV_grp1/Y[31:0]
```

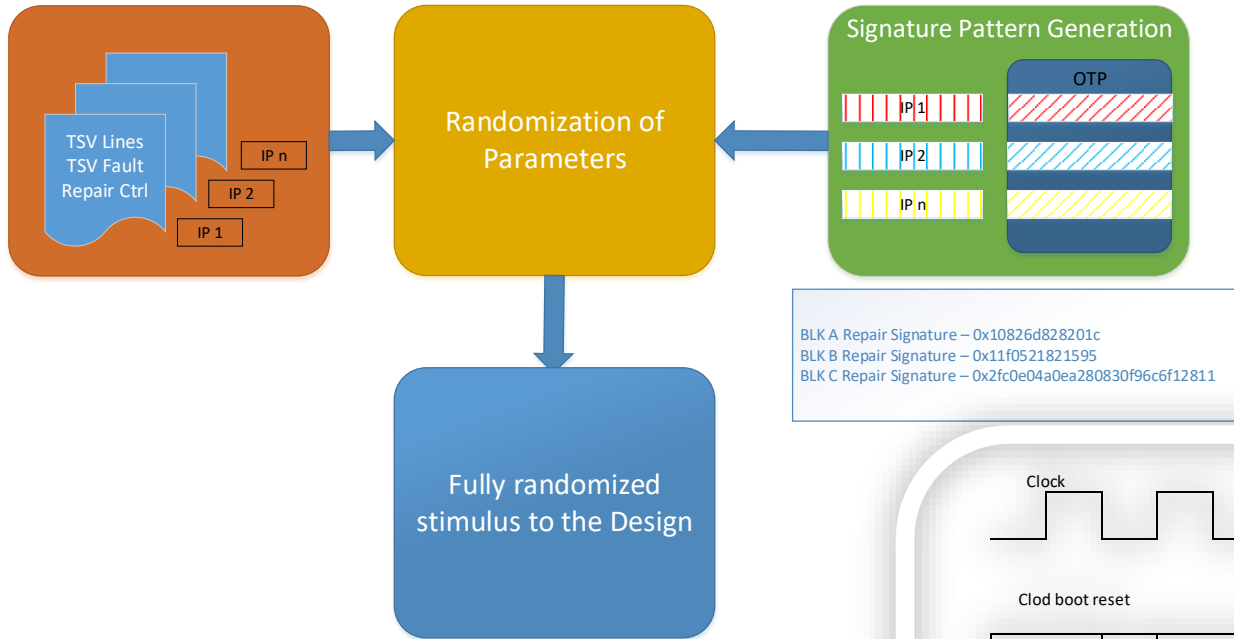
0 -> aaaa_aaaa	0	aaaa_aaaa	5555_5555	ffff_ffff
0 -> aaaa_aaaa	0	aaaa_aaaa	5555_5555	ffff_ffff
0 -> aaaa_aaaa	0	aaaa_aaaa	5555_5555	ffff_ffff
0 -> aaaa_aaaa	0	aaaa_aaaa	5555_5555	ffff_ffff

BOT Die RCV
Signals

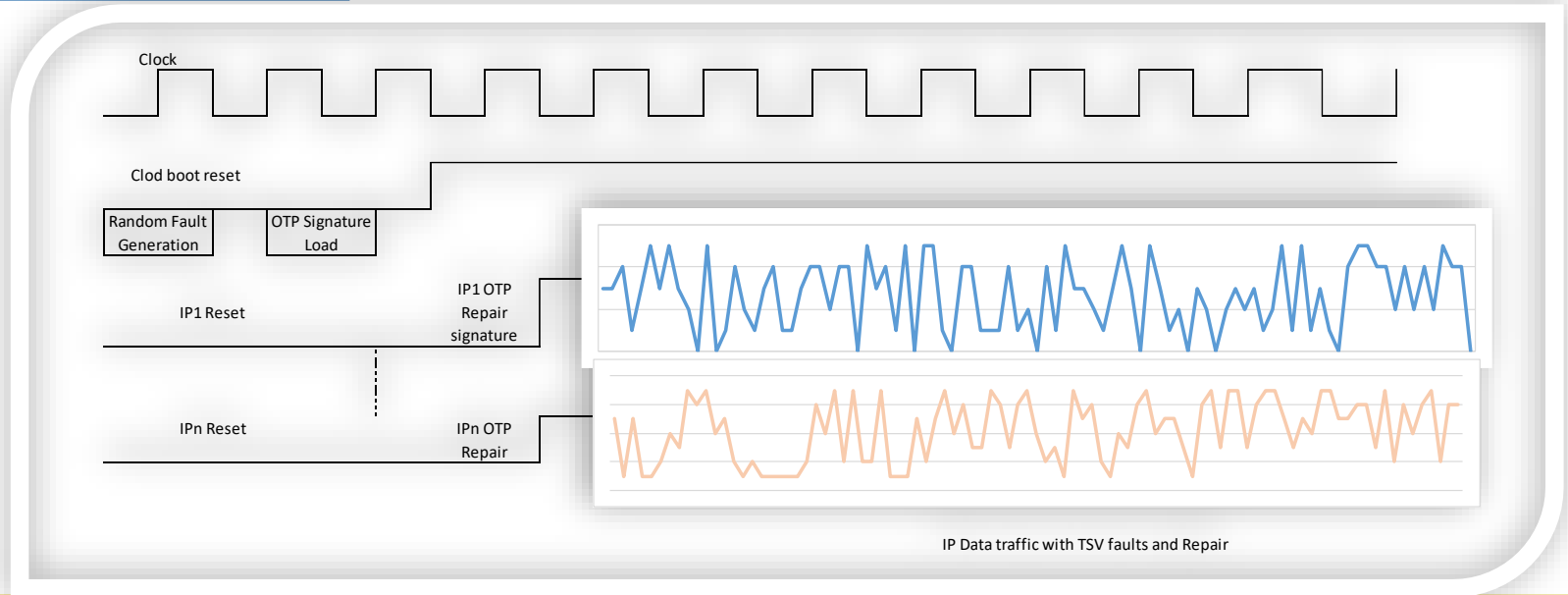
Connectivity Check with
Different Patterns – 0xAA,
0x55, 0xFF and Random data

- As can be seen from the above snapshot, the Y output at the Driver side in TOP die *driver_grp1* is received at the A input of *receiver_grp1* in BOT die.
- The pattern sent are AA, 55, FF and Random data

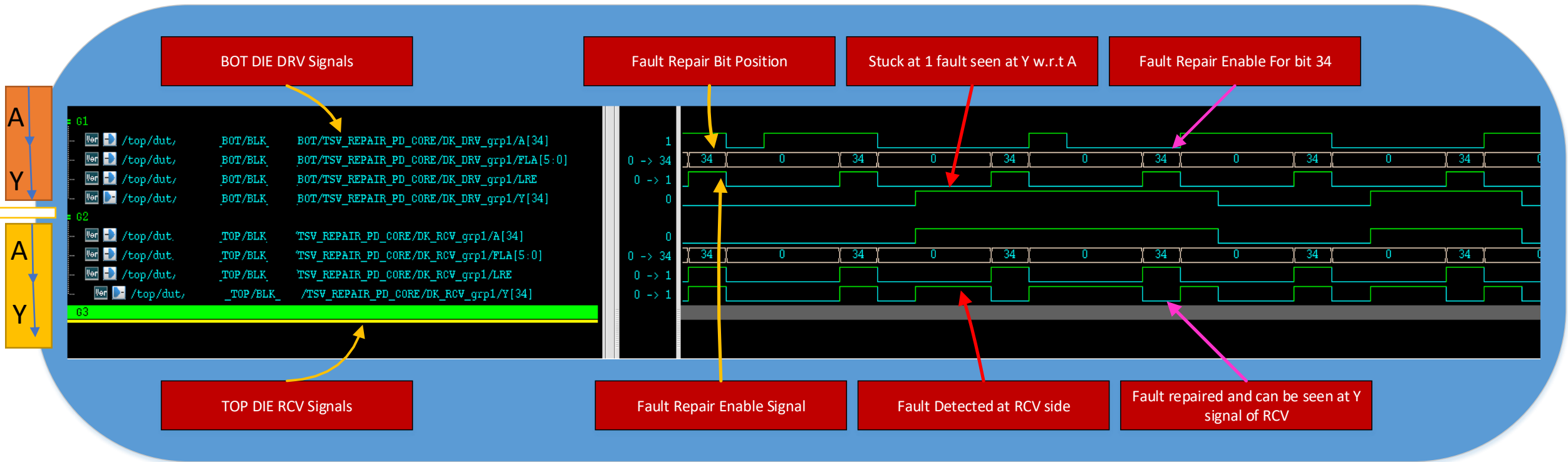
Fault Injection, Repair



BLK A Repair Signature – 0x10826d828201c
BLK B Repair Signature – 0x11f0521821595
BLK C Repair Signature – 0x2fc0e04a0ea280830f96c6f12811



Fault Injection, Repair



Embedded Functional Coverage

Faulty lines

- This coverpoint is used to make sure all the TSV lines are checked for Fault Injection for both stuck-at-0 and stuck-at-1

Signature based Repair check

- This coverpoint covers the TSV line repair based on the control signals and the Repair Signature for all the BLKs which are pre-loaded in OTP. This gives the complete coverage with the combination of TSV line and its control signal for Repair enable and the repairing of the same based on Signature.

Fault pattern

- Additional coverpoint is to check the fault pattern being injected with 0xAA, 0x55 and 0xFF patterns being the bins.

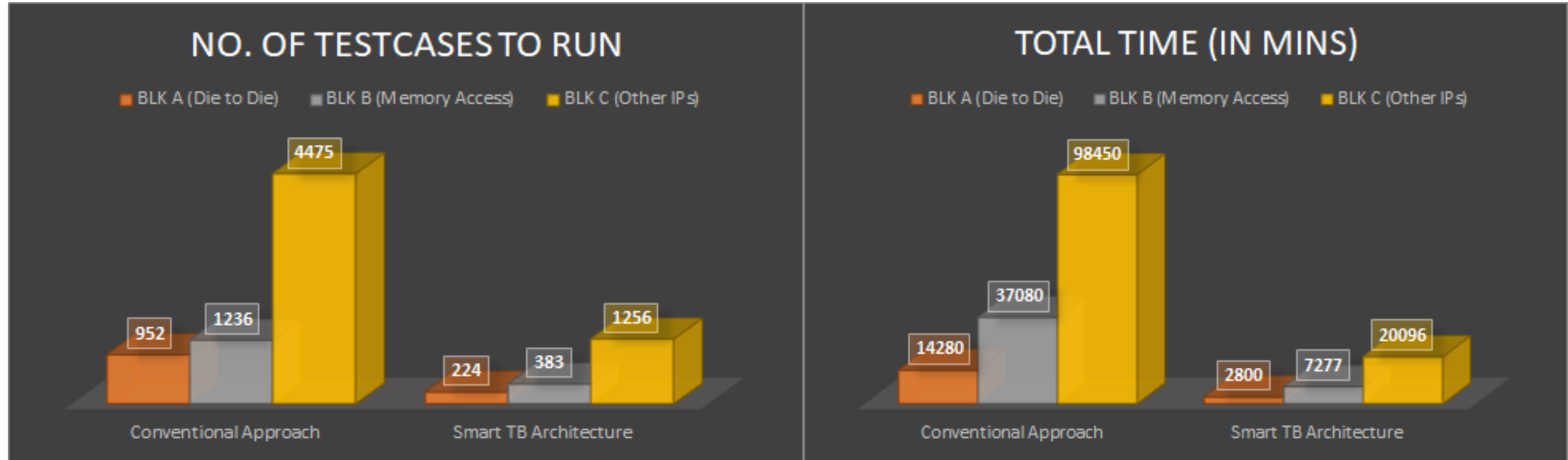


Results & Future Scope

Results – Test cases, Sim Time

BLK	Conventional Approach			Smart TB Architecture			Reduction in time
	No. of Testcases to run	Avg. run time per testcase (in mins)	Total Time (in mins)	No. of Testcases to run	Avg. run time per testcase (in mins)	Total Time (in mins)	
BLK A (Die to Die)	952	15	14280	224	12.5	2800	80.39%
BLK B (Memory Access)	1236	30	37080	383	19	7277	80.37%
BLK C (Other IPs)	4475	22	98450	1256	16	20096	79.59%

Results – Test cases, Sim Time



Results – Coverage

Covergroups

DK_DRV1	
u_TSV_DK_COV	
u_TsvRepairCoverage	100%
repair	100%
faultytsv	100%
DK_DRV2	
u_TSV_DK_COV	
u_TsvRepairCoverage	100%
repair	100%
faultytsv	100%
DK_DRV3	
u_TSV_DK_COV	
u_TsvRepairCoverage	100%
repair	100%
faultytsv	100%

Faulty TSV bins

Name	Overall Average Grade	Overall Covered	Score
(no filter)	(no filter)	(no filter)	(no filter)
Flme[64'h0000000000000000]	100%	1 / 1 (100%)	2880
Flme[64'h0000000000000001]	100%	1 / 1 (100%)	70
Flme[64'h0000000000000002]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000003]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000004]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000005]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000006]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000007]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000008]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000009]	100%	1 / 1 (100%)	120
Flme[64'h000000000000000a]	100%	1 / 1 (100%)	120
Flme[64'h000000000000000b]	100%	1 / 1 (100%)	120
Flme[64'h000000000000000c]	100%	1 / 1 (100%)	120
Flme[64'h000000000000000d]	100%	1 / 1 (100%)	120
Flme[64'h000000000000000e]	100%	1 / 1 (100%)	120
Flme[64'h000000000000000f]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000010]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000011]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000012]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000013]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000014]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000015]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000016]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000017]	100%	1 / 1 (100%)	120
Flme[64'h0000000000000018]	100%	1 / 1 (100%)	121
Flme[64'h0000000000000019]	100%	1 / 1 (100%)	121
Flme[64'h000000000000001a]	100%	1 / 1 (100%)	123
Flme[64'h000000000000001b]	100%	1 / 1 (100%)	121
Flme[64'h000000000000001c]	100%	1 / 1 (100%)	122
Flme[64'h000000000000001d]	100%	1 / 1 (100%)	134
Flme[64'h000000000000001e]	100%	1 / 1 (100%)	136
Flme[64'h000000000000001f]	100%	1 / 1 (100%)	160
Flme[64'h0000000000000020]	100%	1 / 1 (100%)	233
Flme[64'h0000000000000021]	100%	1 / 1 (100%)	317
Flme[64'h0000000000000022]	100%	1 / 1 (100%)	1229

TSV Line bins

Name	Overall Average Grade	Overall Covered	Score
(no filter)	(no filter)	(no filter)	(no filter)
TsvLines[0]	100%	1 / 1 (100%)	80
TsvLines[1]	100%	1 / 1 (100%)	80
TsvLines[2]	100%	1 / 1 (100%)	80
TsvLines[3]	100%	1 / 1 (100%)	80
TsvLines[4]	100%	1 / 1 (100%)	80
TsvLines[5]	100%	1 / 1 (100%)	80
TsvLines[6]	100%	1 / 1 (100%)	80
TsvLines[7]	100%	1 / 1 (100%)	80
TsvLines[8]	100%	1 / 1 (100%)	80
TsvLines[9]	100%	1 / 1 (100%)	80
TsvLines[10]	100%	1 / 1 (100%)	80
TsvLines[11]	100%	1 / 1 (100%)	80
TsvLines[12]	100%	1 / 1 (100%)	80
TsvLines[13]	100%	1 / 1 (100%)	80
TsvLines[14]	100%	1 / 1 (100%)	80
TsvLines[15]	100%	1 / 1 (100%)	80
TsvLines[16]	100%	1 / 1 (100%)	80
TsvLines[17]	100%	1 / 1 (100%)	80
TsvLines[18]	100%	1 / 1 (100%)	80
TsvLines[19]	100%	1 / 1 (100%)	80
TsvLines[20]	100%	1 / 1 (100%)	80
TsvLines[21]	100%	1 / 1 (100%)	80
TsvLines[22]	100%	1 / 1 (100%)	80
TsvLines[23]	100%	1 / 1 (100%)	80
TsvLines[24]	100%	1 / 1 (100%)	80
TsvLines[25]	100%	1 / 1 (100%)	80
TsvLines[26]	100%	1 / 1 (100%)	80
TsvLines[27]	100%	1 / 1 (100%)	80
TsvLines[28]	100%	1 / 1 (100%)	80
TsvLines[29]	100%	1 / 1 (100%)	80
TsvLines[30]	100%	1 / 1 (100%)	79
TsvLines[31]	100%	1 / 1 (100%)	80
TsvLines[32]	100%	1 / 1 (100%)	76
TsvLines[33]	100%	1 / 1 (100%)	52



Conclusion &
Future Scope

Conclusion & Future Scope

- Generic Smart TSV Testbench Automation (Re-use)
- Smart Test case selection (RTL & GLS) and overall TAT reduction
- Early bug detection
- Embedded coverage groups – Test case Pruning
- Power Analysis with TSV faults (SA0, SA1)

Q&A

Thank You